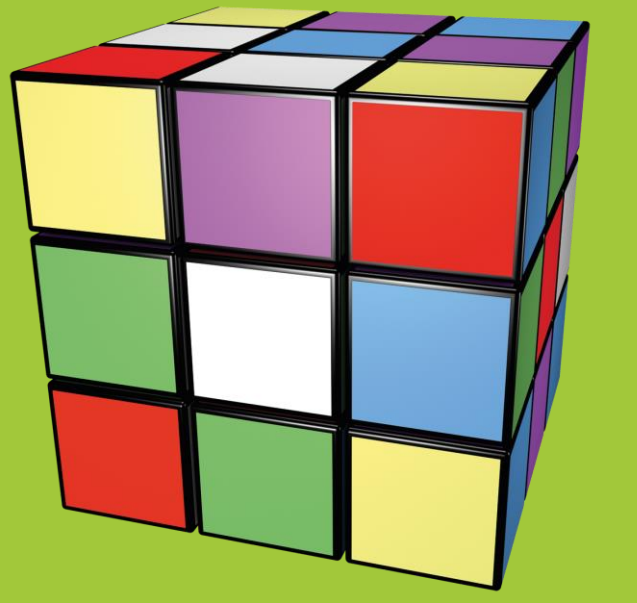


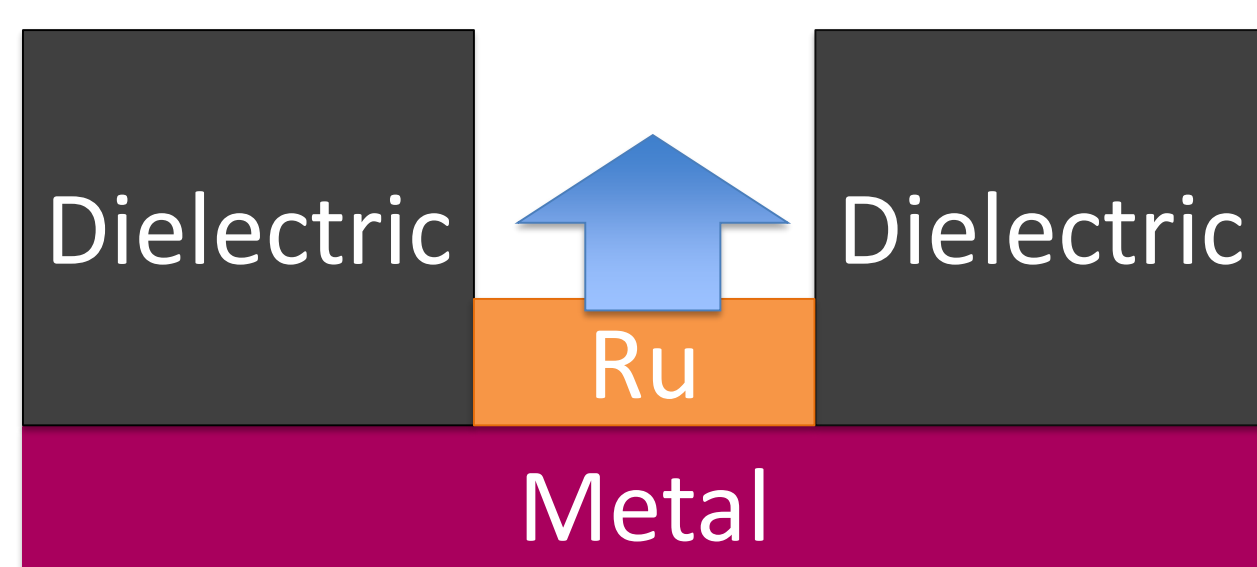


Substrate dependence of ruthenium atomic layer deposition

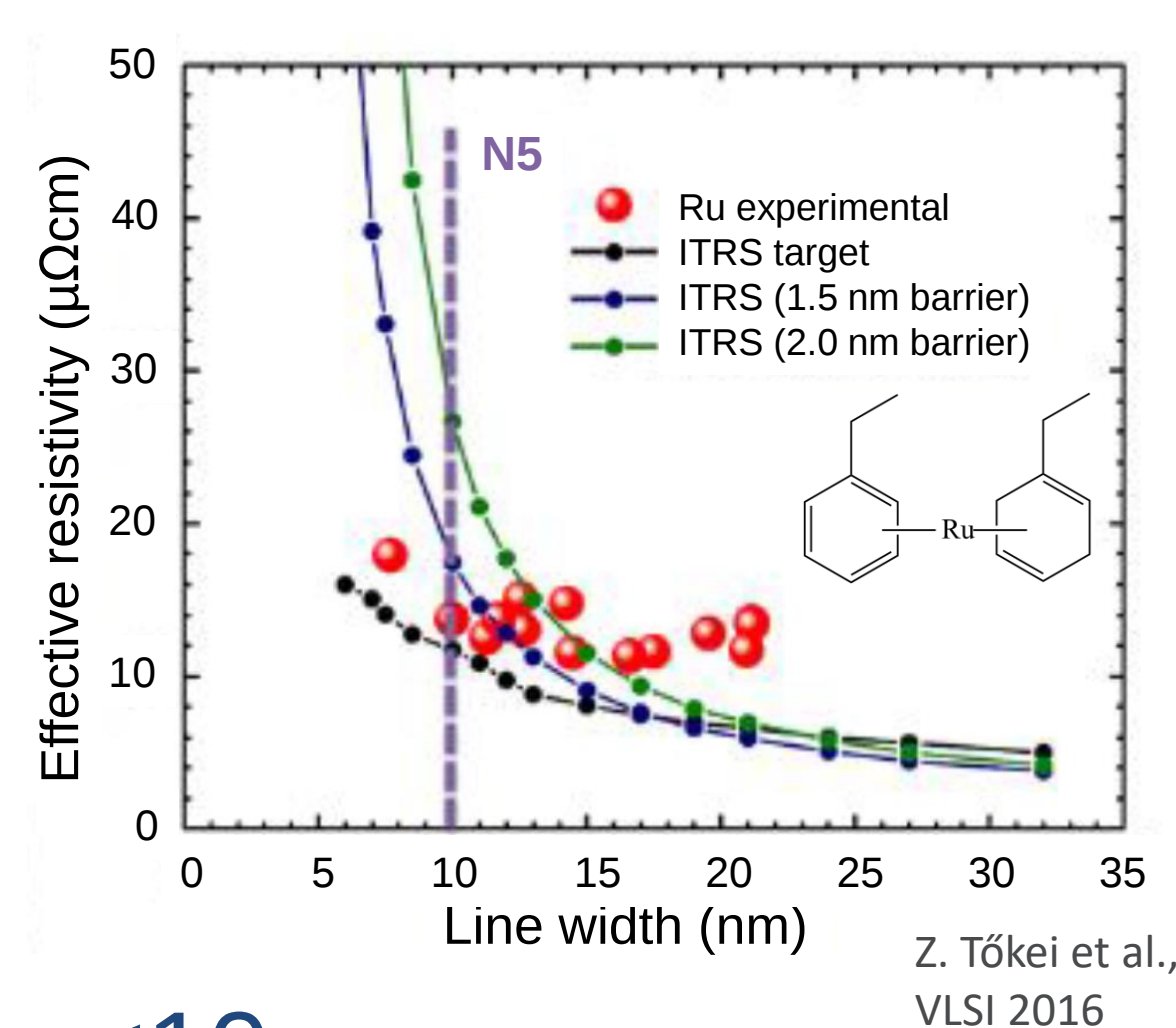
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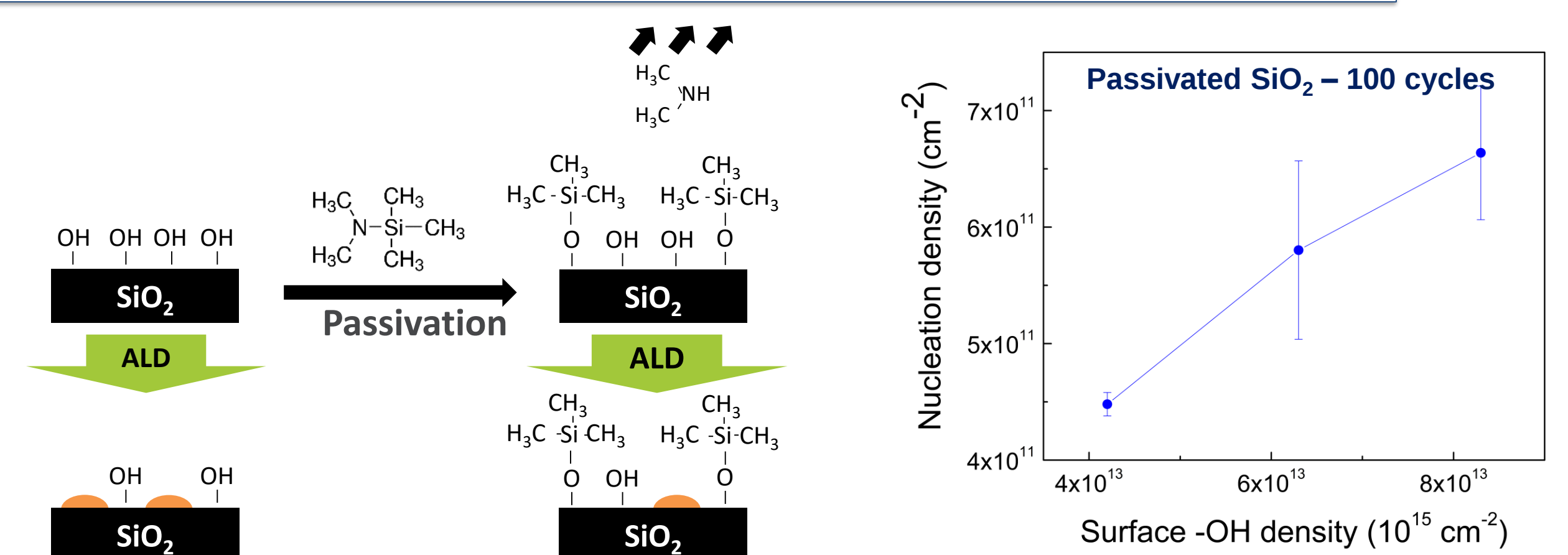
1. Introduction



- Ru promising conductor in <10nm nano-electronic devices
- Void-free filling of small features can be facilitated by bottom-up growth
- Need for selective deposition on the bottom of a feature (metal) and not on the sidewall (dielectric)



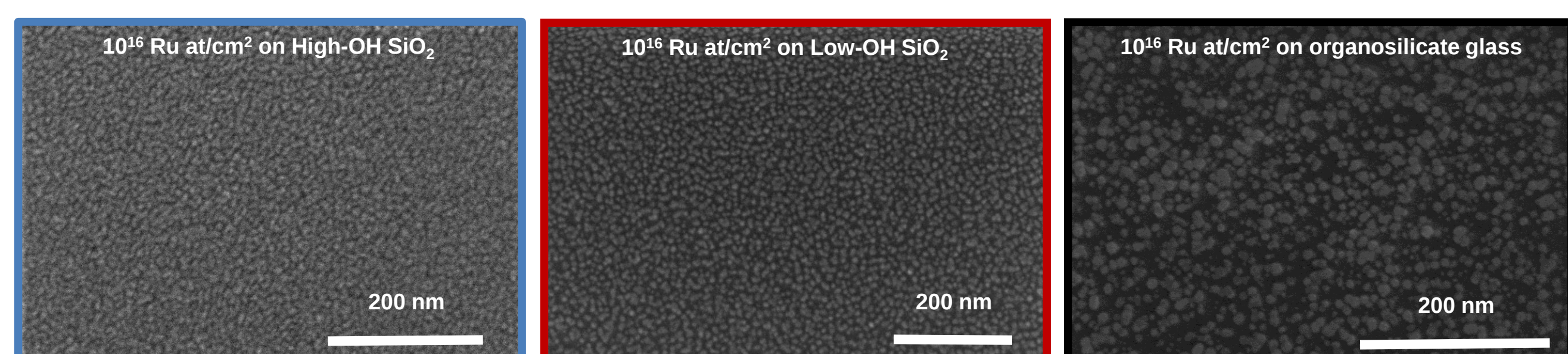
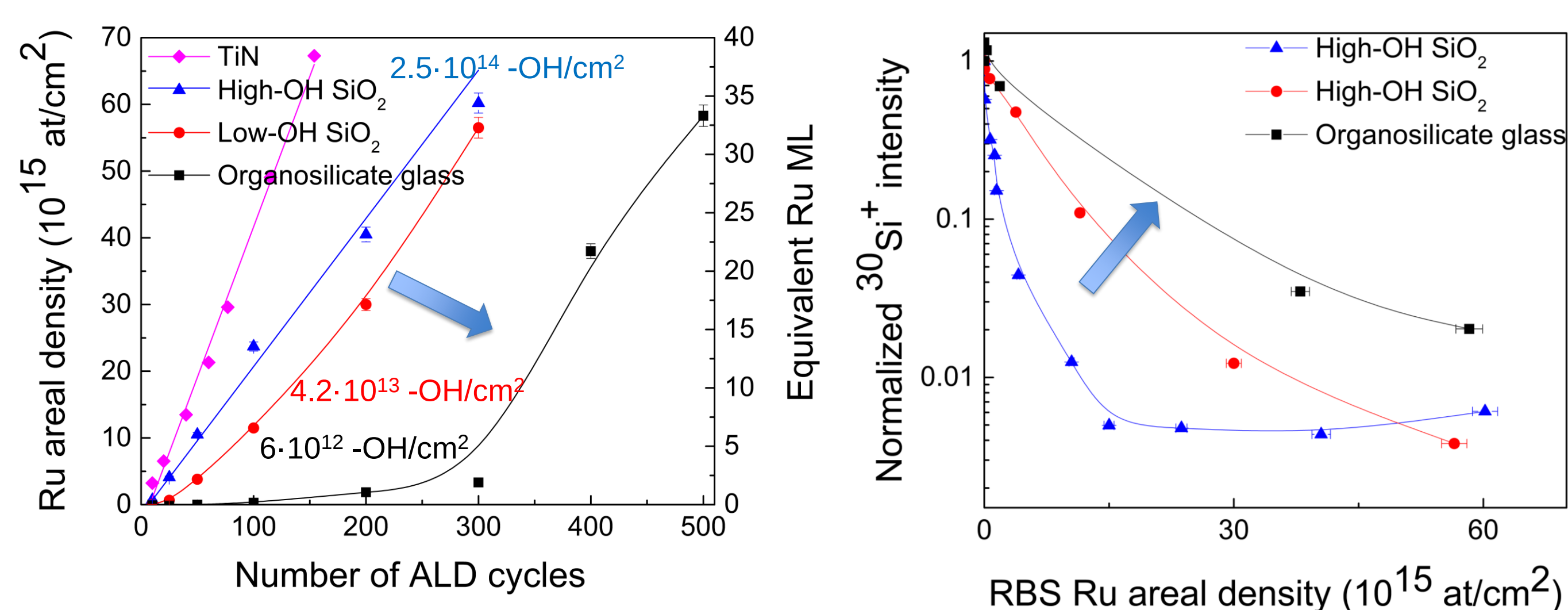
3. Reducing nucleation on SiO₂



- Replacing Si-OH with Si-CH₃ lowers nuc. density

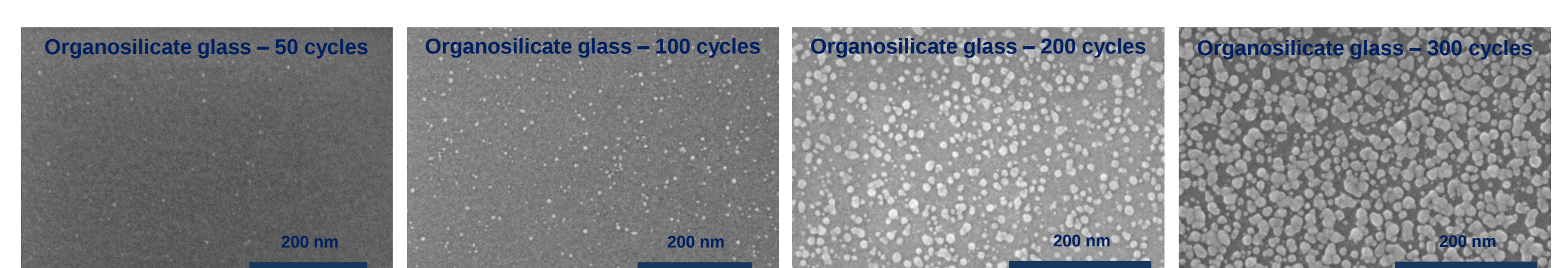
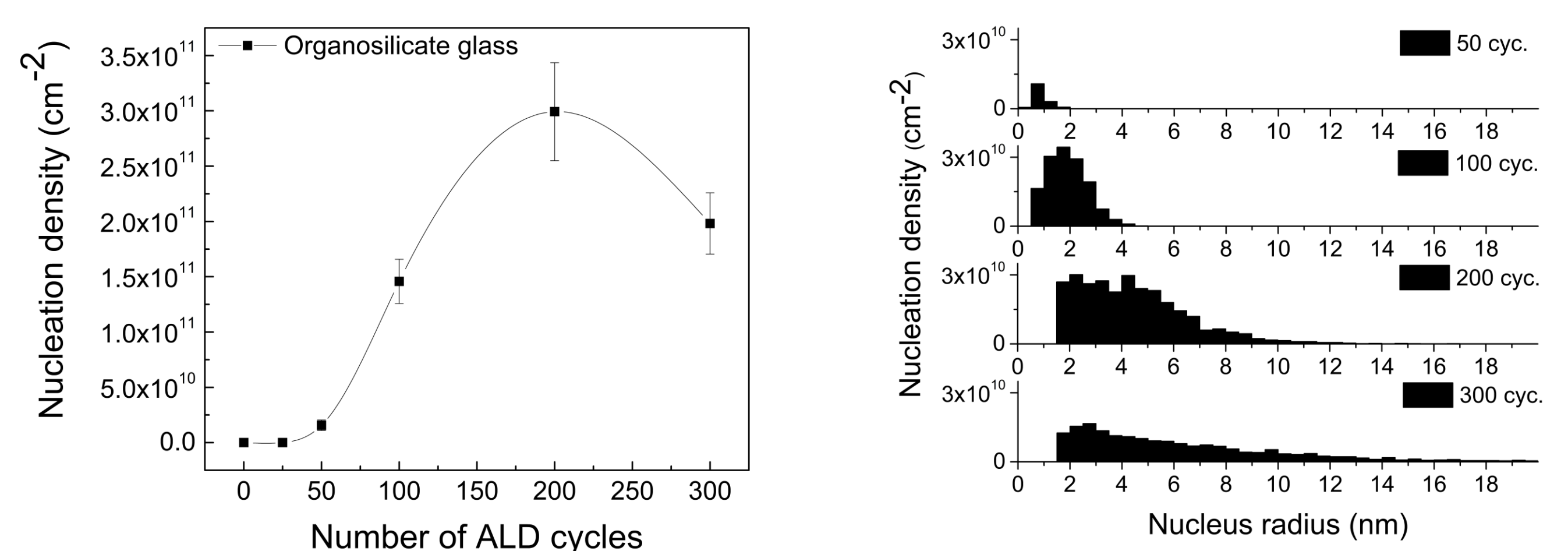
2. Substrate dependence of Ru ALD

- Substrate-dependent Ru ALD process
 - (ethylbenzyl)(1,4-cyclohexadienyl)-ruthenium and oxygen (EBECHRu/O₂)
- High nucleation density and fast film closure on Si-OH terminated substrate
- Low nucleation density and slow film closure on Si-CH₃ terminated substrate



Substrate	Water CA (°)	Surface termination	Surface -OH density (10 ¹⁵ cm ⁻²)	Nucleation density (cm ⁻²)
High-OH SiO ₂	17 ± 1	Si-OH	0.25 ± 0.01	2 · 10 ¹² (25 cycles)
Low-OH SiO ₂	38 ± 2	Si-OH, Si-O-Si	0.042 ± 0.006	7 · 10 ¹¹ (25 cycles)
Organosilicate glass	103 ± 1	Si-CH ₃	< 0.01	2 · 10 ¹⁰ (50 cycles)

4. Nucleation and growth on organosilicate glass



- Low initial nucleation density (1.6 · 10¹⁰ cm⁻²)
- Ru continues to nucleate with increasing cycle number, resulting in a broad size distribution
- Existing nuclei grow with 0.03 nm/cycle

5. Conclusion

- EBECHRu/O₂ ALD is substrate dependent
 - Nucleates readily on Si-OH
 - Nucleation inhibited on Si-CH₃
 - Surfactant-enhanced growth on TiN
- Organosilicate glass is Si-CH₃ terminated and therefore a promising non-growth substrate with low nucleation density (10¹⁰ cm⁻²)